EIPC SPEeDNEWS

The Weekly On-Line Newsletter from the European Institute of Printed Circuits.

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NEWS FROM THE UK

New Sales Manager at Viking Test Ltd.

Veena Bopanna joins Viking Test Limited, the leading UK PCB service and equipment supplier providing quality services and products throughout Europe.

Veena has held sales positions in a multinational PCB manufacturing company in Austria before she started her own firm Multicore E.U. an International trading company which promotes partners from India & Europe in the industrial supply chain. Her extensive industry knowledge and geographical network will further enhance our commitment to expand our business in Europe and India.

Viking is growing its business throughout Europe, India and USA with strong sales in wet process and plating equipment.

Veena can be reached at veena@vikingtest.com

www.vikingtest.com

ICT Annual Symposium will take place at the Black Country Museum, Dudley On 3rd June 2015

Supported by Ventec-Europe

Presentations from :

Trevor Elworthy of Lumejet on Photonic Print Head Technology

Darren Southee of Loughborough University will give a presentation on his supercapacitor work

Francesca Stern of FSC will give her annual 'State of the Nation' address

Professor Martin Goosey will speak on flame retardants

Andy Cobley of Coventry University will update us on the Mesmoproc Project

Les Round of Spirit Circuits will give a presentation on his LED Work

Ian Mayoh/Martin Cotton of Ventec-Europe will update us on recent work

Emma Goosey will bring us up to date on our Crabs Project STOWURC

Registration is £85:00 and will also include Museum Entry

Tabletops are available at £50:00

www.InstICT.org

IMAPS UK ADVANCED PACKAGING WORKSHOP – 4th June 2015

IMAPS-UK are pleased to announce their forthcoming Advanced Packaging Interconnect Workshop taking place on 04 June 2015.

This unique Workshop, organised by IMAPS-UK and supported by The CPI is your opportunity to learn about the technology of electronic device packaging interconnect and discover how to select the right solutions for your new and emerging applications.

The programme will consist of 4 workshop sessions on Advanced Packaging Interconnect aspects, followed by 6 short case studies covering a range of related applications and technologies. Attendees will also be invited to take a look at the assembly lines in the Centre for Process Innovation (CPI) Sedgefield facilities.

The workshop, which will be limited in numbers, is aimed at electronic system developers, manufacturers and end-users as well as design companies that now need to understand this very important technology area. It will review the key issues of package interconnects, how to address these and how to develop optimum solutions.

Session One - Advanced Packaging Overview: ASE
Session Two - Flip Chip & Bumping: STFC
Session Three - Sintering: Heraeus
Session Four - Flexible Interconnect: CPI
Session Five & Six - Case Studies
Plus: CPI Facility Line Tour

There are limited places available and we expect the spaces to fill up quickly. So, as IMAPS-UK members or previous attendees at one of our events, we are offering you the first opportunity to reserve your place.

Please visit our website for more details: http://uk.imapseurope.org/index.php/event-calender/details/58-APIW-15

Andy Longford, IMAPS-UK Secretariat
Telephone: + 44 (0)131 202 9004
Email: andy.longford@imaps.org.uk